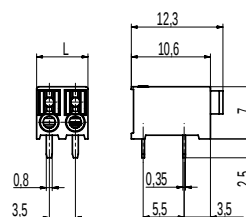
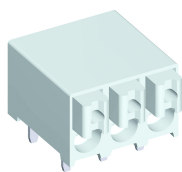
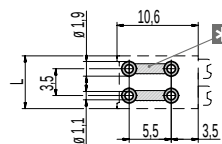


830-A-111-THR

PCB connector for SMD
Push-In connection



PCB LAYOUT (RECOMMENDATION)



L = (No. of poles) x pitch
L1 = (No. of poles - 1) x pitch
Solder paste thickness:
0,15 - 0,2 mm
solder pad, outside
diameter: $\varnothing$ 1,9 mm

* Both solder pads of
each pole can be
connected together.

MATERIAL

Moulding	PA HT, white, V-0
Comparative Tracking Index	CTI $\geq$ 600
Insulating Group	I
Temperature Range	-40°C up to 120°C; reflow solder temperature peak max. 255°C acc. to DIN EN 61760-1
Terminal body	Tin plated copper alloy
Spring	Stainless steel

OPTIONS / ACCESSORIES

- Consecutive numbering
- Special marking according to drawing
- Black colour on request
- Tape-on-Reel on request

GENERAL INFORMATION

Pitch	3,5 mm
No. of poles	2 + 3
Areas of application	Lighting technology, devices

TECHNICAL DATA

Clamping Range	solid / stranded / AWG 0,2 - 1,0 mm ² / 0,2 - 0,75 mm ² / 24 - 18 AWG		
Rated Cross Section	1 mm ² (starr / solid) / 0,75 mm ²		
Wire Stripping Length	7,5 mm $\pm$ 0,5 mm		
Overvoltage Category	III	III	II
Pollution Severity Level	3	2	2
Rated Voltage	160 V	160 V	320 V
Rated Impulse Voltage	2,5 kV	2,5 kV	2,5 kV
Rated Insulation Voltage	130 V acc. to EN 60998-1		
Rated Current	13,5 A apply to 1 mm ² solid 9 A apply to 0,75 mm ²		
Soldering process	Reflow solder		
Hole in PCB	$\varnothing$ 1,1 mm		

APPROVALS

	Current [A]	Voltage [V]	Group	AWG	[Nm]
	6	300	B	24 - 18	

CONFIGURATIONS

Poles	Part number	Article number	Length (L)	Packaging	PU
2	830-A-111-THR/02	10.813.052	6,90 mm	Box	250
3	830-A-111-THR/03	10.813.053	10,40 mm	Box	250